

ABSTRACT

MANUFACTURE OF PREPREGS AND LAMINATES WITH
RELATIVELY LOW DIELECTRIC CONSTANT FOR PRINTED
CIRCUIT BOARDS

- _____The present invention is directed to filled prepregs, laminates, printed circuit boards comprising a reinforcing material impregnated with a cured polymeric resin, the cured polymeric resin comprising multicellular polymeric microspheres as a filler. Pre-pregs, laminates and printed circuit boards prepared by this method have reduced dielectric constant as low as 3.0, depending upon the resin system of the matrix. In addition, such laminates and printed circuit boards have enhanced electrical, thermal and mechanical properties as well as improved machinability, low density and a uniform appearance.
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